



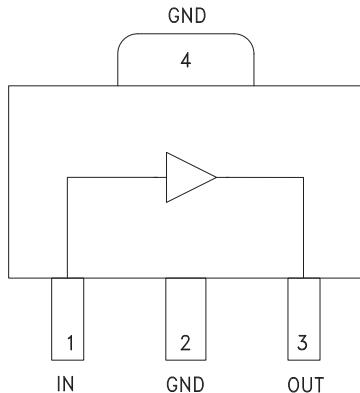
**HIGH IP3, LOW NOISE
AMPLIFIER, 0.2 - 4.0 GHz**

Typical Applications

The HMC639ST89(E) is ideal for:

- Cellular / PCS / 3G
- WiMAX, WiBro, & Fixed Wireless
- CATV & Cable Modem
- Microwave Radio
- IF and RF Sections

Functional Diagram



Features

- Low Noise Figure: 2.3 dB
- High P1dB Output Power: +22 dBm
- High Output IP3: +38 dBm
- Gain: 13 dB
- 50 Ohm I/O's - No External Matching
- Industry Standard SOT89 Package

General Description

The HMC639ST89(E) is a GaAs pHEMT, High Linearity, Low Noise, Wideband Gain Block Amplifier covering 0.2 to 4.0 GHz. Packaged in an industry standard SOT89, the amplifier can be used as either a cascadable 50 Ohm gain stage, a PA Pre-Driver, a Low Noise Amplifier, or a Gain Block with up to +22 dBm output power. This versatile Gain Block Amplifier is powered from a single +5V supply and requires no external matching components. The internally matched topology permits this amplifier to be readily ported between virtually any printed circuit board material, regardless of its dielectric constant, thickness, or composition.

Electrical Specifications, Vs= 5V, TA = +25° C

Parameter	Min	Typ.	Max	Min.	Typ.	Max.	Units
Frequency Range		0.7 - 2.2			0.2 - 4.0		GHz
Gain	10	13		6	10		dB
Gain Variation Over Temperature		0.01	0.02		0.01	0.02	dB/ °C
Input Return Loss		12			12		dB
Output Return Loss		12			14		dB
Reverse Isolation		20			20		dBm
Output Power for 1 dB Compression (P1dB)	19	21		20	22		dB
Output Third Order Intercept (IP3)	35	38		35	38		dBm
Noise Figure		2.3			2.5		dB
Supply Current (Icq)	90	110	120	90	110	120	mA

Note: Data taken with broadband bias tee on device output.

HMC639* PRODUCT PAGE QUICK LINKS

Last Content Update: 02/23/2017

COMPARABLE PARTS

View a parametric search of comparable parts.

EVALUATION KITS

- HMC639ST89 Evaluation Board

DOCUMENTATION

Application Notes

- AN-1363: Meeting Biasing Requirements of Externally Biased RF/Microwave Amplifiers with Active Bias Controllers
- Broadband Biasing of Amplifiers General Application Note
- MMIC Amplifier Biasing Procedure Application Note
- Thermal Management for Surface Mount Components General Application Note

Data Sheet

- HMC639 Data Sheet

TOOLS AND SIMULATIONS

- HMC639 S-Parameter

REFERENCE MATERIALS

Quality Documentation

- Package/Assembly Qualification Test Report: 3 Lead Plastic SOT89 Package (QTR: 10002 REV: 02)
- Semiconductor Qualification Test Report: PHEMT-F (QTR: 2013-00269)

DESIGN RESOURCES

- HMC639 Material Declaration
- PCN-PDN Information
- Quality And Reliability
- Symbols and Footprints

DISCUSSIONS

View all HMC639 EngineerZone Discussions.

SAMPLE AND BUY

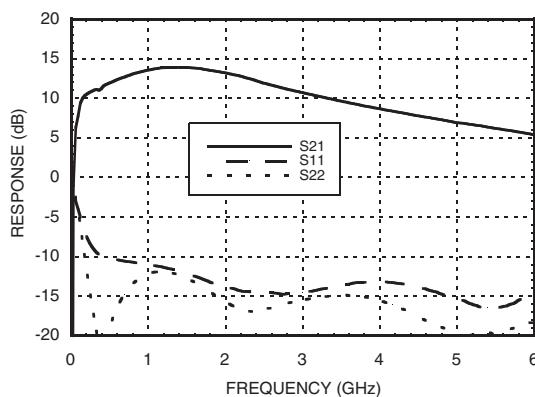
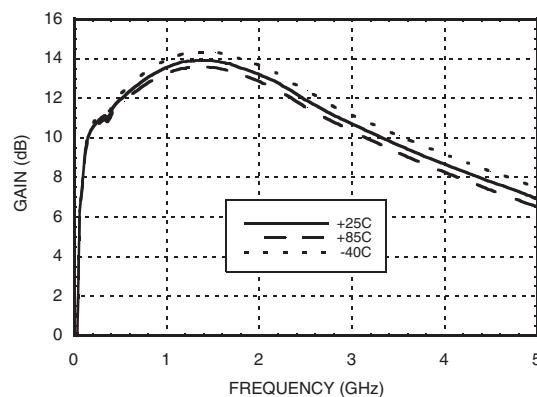
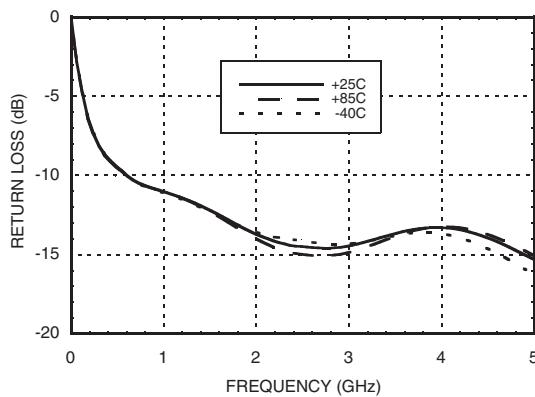
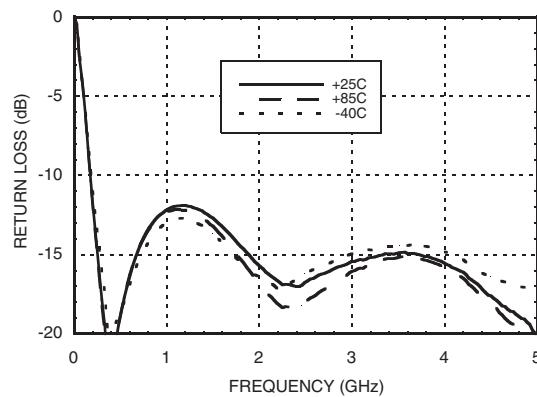
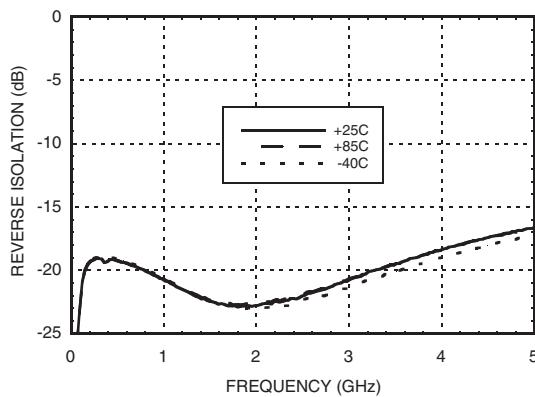
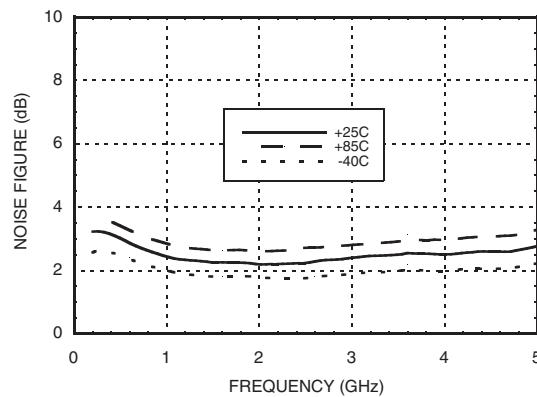
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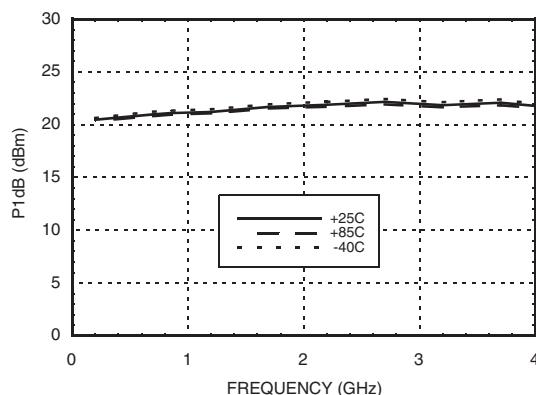
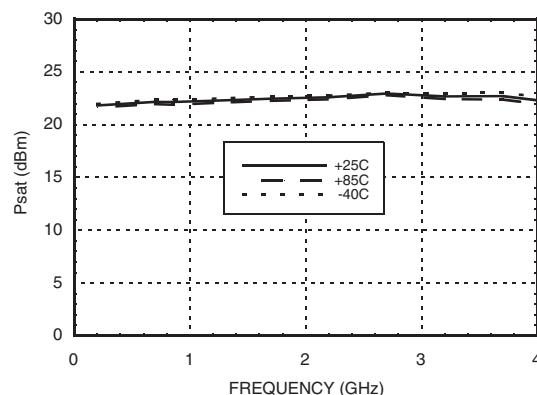
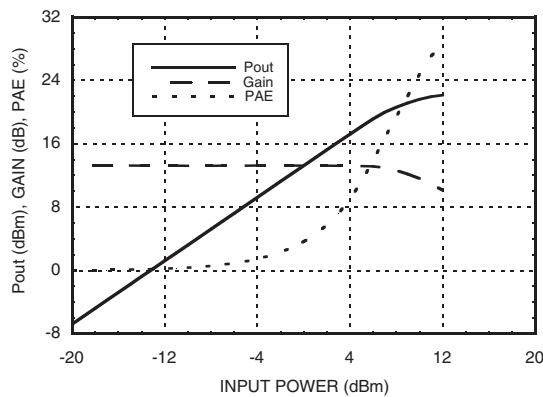
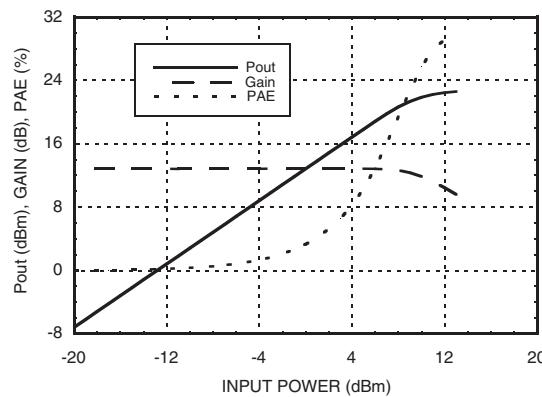
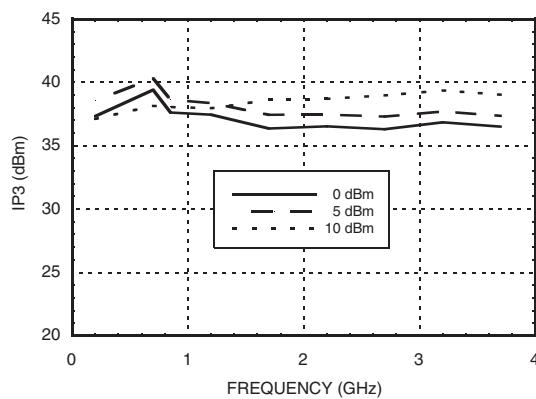
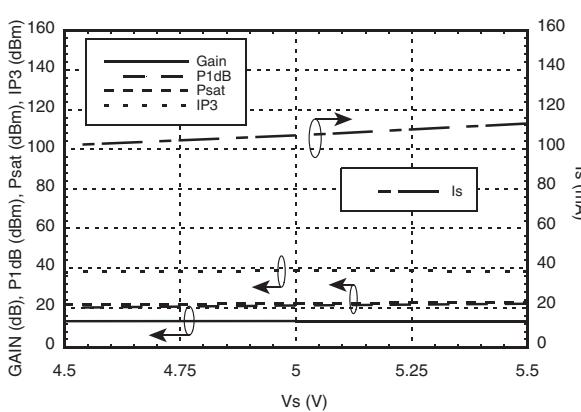
TECHNICAL SUPPORT

Submit a technical question or find your regional support number.

DOCUMENT FEEDBACK

Submit feedback for this data sheet.


**HIGH IP3, LOW NOISE
AMPLIFIER, 0.2 - 4.0 GHz**
9
Broadband Gain & Return Loss

Gain vs. Temperature

Input Return Loss vs. Temperature

Output Return Loss vs. Temperature

Reverse Isolation vs. Temperature

Noise Figure vs. Temperature


**P1dB vs. Temperature****Psat vs. Temperature****Power Compression @ 850 MHz****Power Compression @ 2200 MHz****Output IP3 vs. Output Tone Power****Gain, Power, Output IP3 & Supply Current vs. Supply Voltage @ 850 MHz**

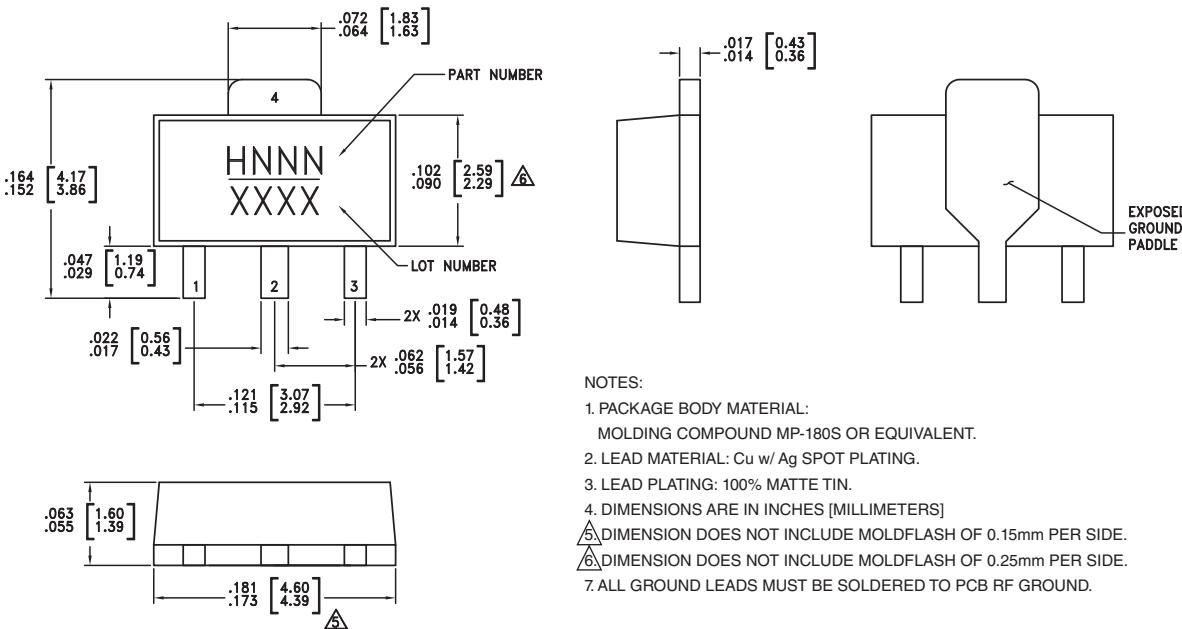

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Absolute Maximum Ratings

Collector Bias Voltage (Vcc)	+5.5 Volts
RF Input Power (RFIN)(Vcc = +5 Vdc)	+15 dBm
Channel Temperature	150 °C
Continuous Pdiss (T = 85 °C) (derate 13.3 mW/°C above 85 °C)	0.86 W
Thermal Resistance (Channel to lead)	75.6 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C
ESD Sensitivity (HBM)	Class 1A


**ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS**
9
AMPLIFIERS - LINEAR & POWER - SMT

Outline Drawing



Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking ^[3]
HMC639ST89	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 ^[1]	H639 XXXX
HMC639ST89E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 ^[2]	H639 XXXX

[1] Max peak reflow temperature of 235 °C

[2] Max peak reflow temperature of 260 °C

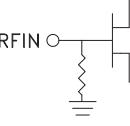
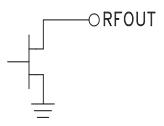
[3] 4-Digit lot number XXXX

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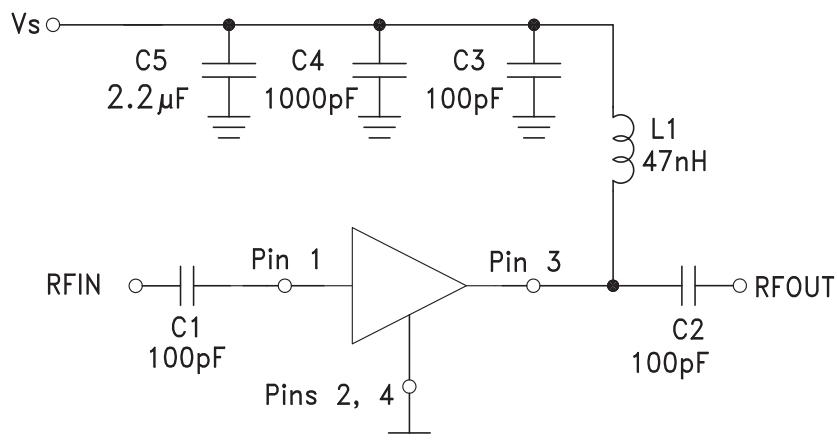
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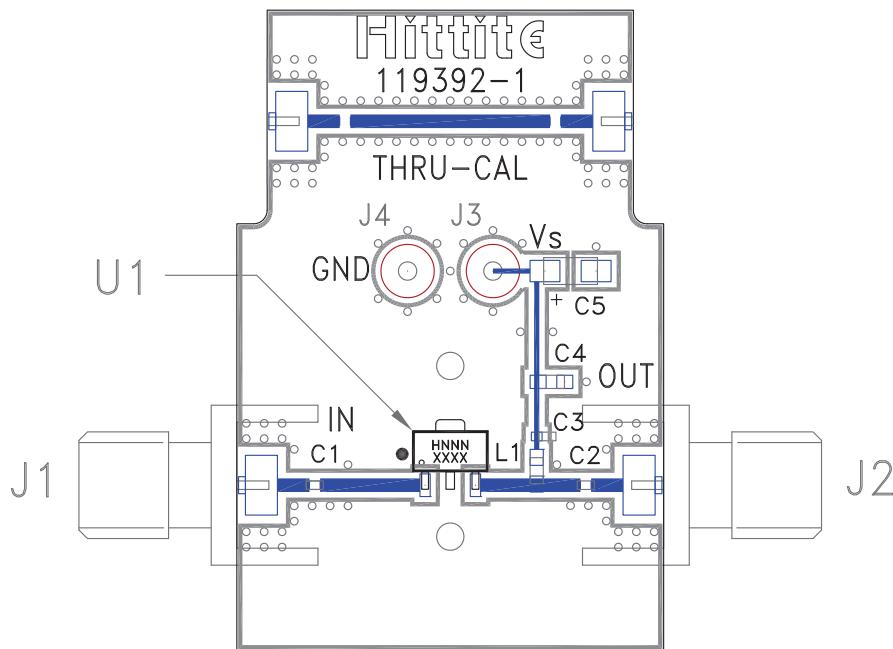

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Pin Descriptions

Pin Number	Function	Description	Interface Schematic
1	RFIN	This pin is DC coupled. An off-chip DC blocking capacitor is required.	
3	RFOUT	RF Output and DC BIAS for the amplifier. See Application Circuit for off-chip components.	
2, 4	GND	These pins and package bottom must be connected to RF/DC ground.	

Application Circuit




Evaluation PCB

List of Materials for Evaluation PCB 119394^[1]

Item	Description
J1 - J2	PCB Mount SMA Connector
J3 - J4	DC Pin
C1 - C3	100 pF Capacitor, 0402 Pkg.
C4	1000 pF Capacitor, 0603 Pkg.
C5	2.2 μ F Capacitor, Tantalum
L1	47 nH Inductor, 0603 Pkg.
U1	HMC639ST89(E)
PCB [2]	119392 Evaluation PCB

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: FR4

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and package bottom should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation board should be mounted to an appropriate heat sink. The evaluation circuit board shown is available from Hittite upon request.